Amendments to the Claims

1-10. (Cancelled).

11. (New) A method for gluing a circuit component to a circuit substrate comprising:

seizing a circuit component using a gripper;

moving the gripper towards a surface of the circuit substrate a first time to a target distance from the surface at which adhesive applied between the circuit component and the circuit substrate is pressed;

releasing the circuit component and removing the gripper from the circuit component;

turning the gripper around an axis perpendicular to the surface of the circuit substrate;

moving the gripper to the target distance a second time; and

removing the gripper.

12. (New) The method of claim 11 further comprising when moving the gripper toward the substrate the first time, detecting a counteracting force opposing the movement of the gripper and defining the target distance to be the distance at which the opposing force reaches a predetermined value.

13. (New) The method of claim 12 further comprising detecting a local coordinate of the target distance the first time and wherein moving the gripper into the target distance a second time comprises moving the gripper to the detected local coordinate.

14. (New) The method of claim 11 wherein turning the gripper around an axis perpendicular to the surface of the circuit substrate comprises turning the gripper through a turning angle of approximately 180 degrees.

15. (New) The method of claim 11 further comprising metering the adhesive to yield an adhesive layer of less than 10 mm thickness.

16. (New) The method of claim 15 wherein the adhesive layer is approximately 5 mm thick.

17. (New) The method of claim 11 further comprising applying the adhesive in advance to the circuit substrate as a regular pattern of adhesive dots.

18. (New) The method of claim 17 further comprising applying additional individual adhesive dots closer to a corner of the circuit component than the dots of the regular pattern of adhesive dots.

19. (New) The method of claim 17 further comprising applying one or more additional dots to a central area of the regular pattern.

20. (New) The method of claim 11 wherein the gripper includes an abutment surface that abuts against at least two opposite edges of a surface of the circuit component that faces away from the circuit substrate.

21. (New) The method of claim 11 wherein seizing a circuit component using a gripper comprises placing a suction opening of the gripper over the circuit component to be seized, and creating a vacuum between the suction opening and the circuit component.